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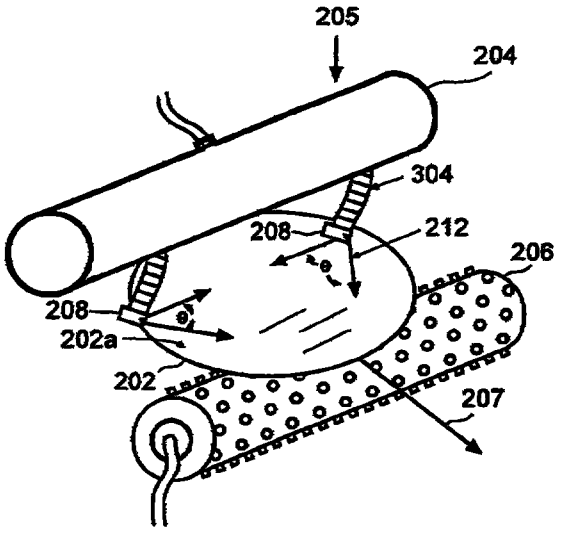
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(54) Title: METHOD AND SYSTEM OF CLEANING A WAFER AFTER CHEMICAL MECHANICAL POLISHING OR PLASMA PROCESSING



(57) Abstract: A method and system are provided for cleaning a surface of a semiconductor wafer following a fabrication operation. The system includes a brush box, which has a fluid manifold (204) and at least one nozzle (208). The nozzle (208) is connected to the fluid manifold (204) by a flexible conduit (304). The nozzle (208) is configured to spray a liquid onto the surface of the wafer at an application angle and at a fan angle (θ). The application angle is defined between a plane of the surface of the wafer (202) and a spraying plane of the liquid. The fan angle (θ) and the application angle are configured such that the spraying liquid covers the surface of the wafer (202) in a quiescent manner.

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